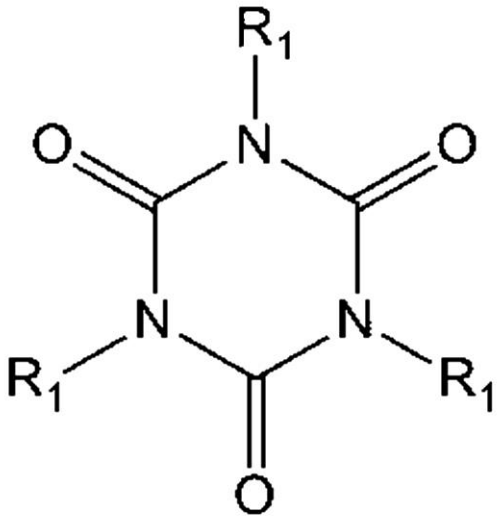
[Claims]

[Claim 1]

A negative-acting photosensitive resin composition comprising:

(A) a compound having a triazine ring represented by the following formula (1):

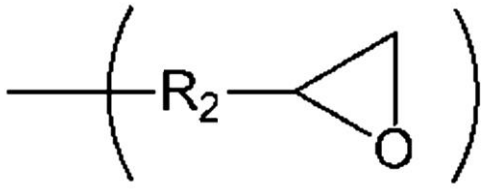
[Chemical Formula 1]



(1)

wherein all of R_1s represent an organic group represented by the following formula (1-1):

[Chemical Formula 2]

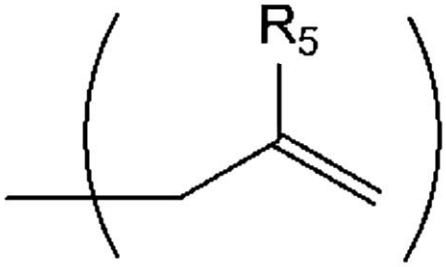


(1-1)

wherein R_2 represents a n-propylene group, or

one of R_1s represents an organic group represented by the above formula (1-1) wherein R_2 represents a methylene group and the other two of R_1s each represent an organic group represented by the following formula (1-4):

[Chemical Formula 3]



(1-4)

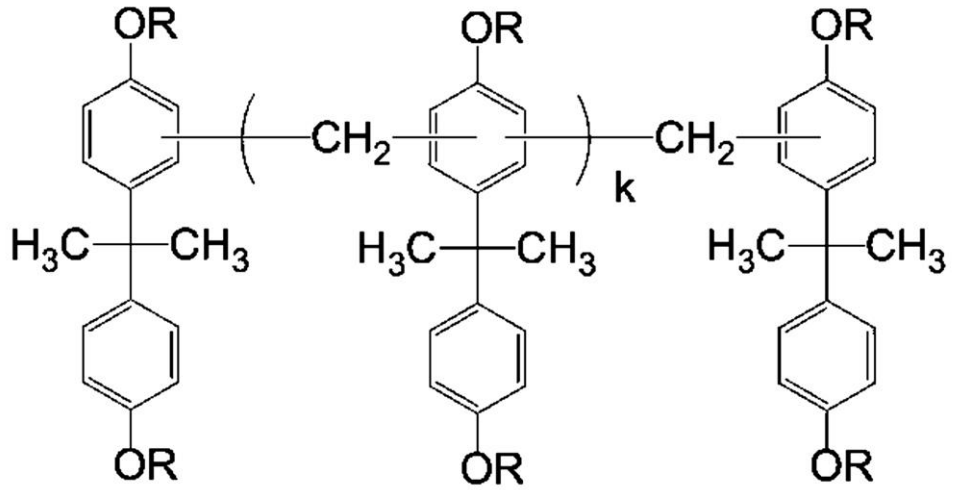
wherein R_5 represents a hydrogen atom;

(B) an epoxy resin having a benzene backbone and at least two epoxy groups in one molecule and having an epoxy equivalent weight of 500 g/eq or less,

wherein the epoxy resin (B) is a combination of:

an epoxy resin (B-1) represented by the following formula (2):

[Chemical Formula 4]

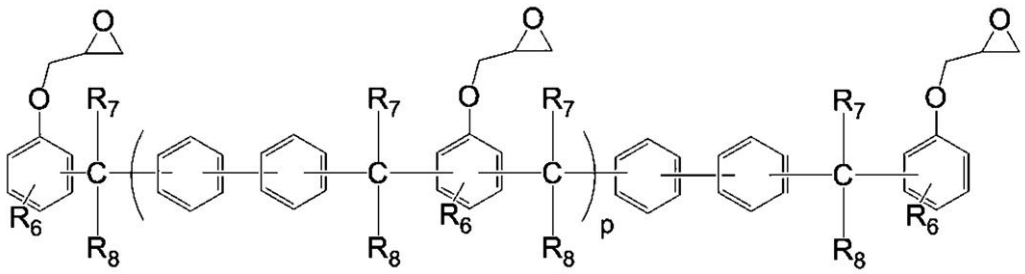


(2)

wherein Rs each independently represent a glycidyl group or a hydrogen atom, with the proviso that at least two Rs are glycidyl groups, and k represents an average and is a real number within a range of 0 to 30,

an epoxy resin (B-2) represented by the following formula (3):

[Chemical Formula 5]

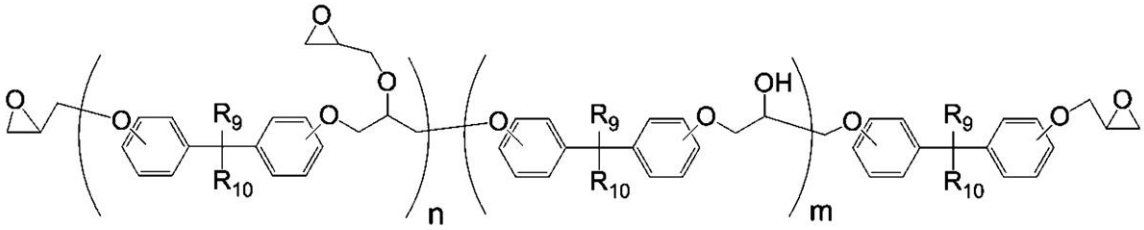


(3)

wherein R_6, R_7, and R_8 each independently represent a hydrogen atom or a $C_{1\text{-}4}$ alkyl group, and p represents an average and is a real number within a range of 1 to 30, and

an epoxy resin (B-3) represented by the following formula (4):

[Chemical Formula 6]



(4)

wherein n and m each represent an average, n is a real number within a range of 1 to 30, m is a real number within a range of 0.1 to 30, and R_9 and R_{10} each independently represent a hydrogen atom, a $C_{1\text{-}4}$ alkyl group, or a trifluoromethyl group; and

(C) a cationic photopolymerization initiator,

the negative-acting photosensitive resin composition being configured such that

the content of the compound (A) represented by formula (1) relative to the epoxy resin (B) is 1 to 50 mass%, and

the epoxy resin (B) satisfies the following condition (i):
condition (i): having a weight-average molecular weight of 500 or more.

[Claim 2]
A dry film resist comprising the negative-acting photosensitive resin composition according to claim 1.

[Claim 3]
A cured product of the negative-acting photosensitive resin composition according to claim 1 or the dry film resist according to claim 2.

[Claim 4]
A wafer level package comprising the cured product according to claim 3.

[Claim 5]
An adhesive layer between a substrate and an adherend, comprising the cured product according to claim 3.